

IN THE SPECIFICATION:

Please amend the specification as follows:

Please replace paragraph 1 on page 23 of the specification as follows:

Hereinafter, specific examples of the present invention will be described.

The solder balls of this preferred embodiment are preferably formed by an electroplating process. However, the electroplating process does not have to be carried out as described below but may be performed following a known procedure. For instance, an alkane sulfonic acid bath (see Japanese Patent Application Laid-Open Publications Nos. 8-13185 and 12-34593, for example) will be used as a plating solution for plating an Sn-Ag alloy in the following specific examples. Alternatively, a gluconic acid-iodide bath (see Japanese Patent Application Laid-Open Publication No. 10-36995, for example) or a tartaric acid bath (see "Su-Ag Alloy Electrodeposition from L-Tartrate Complex Bath" Surface Technology ~~49.758~~ Vol. 49, No. 7 (1998) pp.759-763, for example) may also be used.